

ABSTRACT OF THE DISCLOSURE

An integrated circuit package and a process for forming the same. The package includes a semiconductor die with bond pads, a die attachment pad on which the semiconductor die is attached, and a substrate on which the die attachment pad is positioned. A non-conductive lead finger mounting ring is attached to the peripheral region of the substrate. Package leads are attached to the lead finger mounting ring, and are electrically coupled to the bond pads via bond wires. The bond wires are enclosed in an epoxy material having an approximately rounded top surface. The die, the die attachment pad, the substrate, the lead finger mounting ring, and the epoxy material are enclosed in a mold compound.

Patent for the above